



040804

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of: Gurtej S. Sandhu et al.

Title: METHOD FOR FORMING A METALLIZATION LAYER

Attorney Docket No.: 303.085US7

Customer No.: 21186

 17513 U.S.PTO
 10/820291


040804

PATENT APPLICATION TRANSMITTAL

MAIL STOP PATENT APPLICATION

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

We are transmitting herewith the following attached items and information (as indicated with an "X"):

Return postcard.

DIVISIONAL of prior Patent Application No.(10/217618) (under 37 CFR 1.53(b)) comprising:

Specification (13 pgs, including claims numbered 1 through 32 and a 1 page Abstract).

Formal Drawing(s) (2 sheets).

Copy of signed Combined Declaration and Power of Attorney (7 pgs) from prior application.

Incorporation by Reference: *The entire disclosure of the prior application, from which a copy of the oath or declaration is supplied herewith, is considered as being part of the disclosure of the accompanying application and is hereby incorporated by reference therein.*

Check in the amount of \$1330.00 to pay the filing fee.

Prior application is assigned of record to Micron Technology, Inc..

Information Disclosure Statement (2 pgs), Form 1449 (1 pgs)

References NOT enclosed, cited in prior application.

A Communication Concerning Related Applications (1 pg.).

The filing fee has been calculated below as follows:

	No. Filed	No. Extra	Rate	Fee
TOTAL CLAIMS	32-20	12	x 18.00 =	\$216.00
INDEPENDENT CLAIMS	7-3	4	x 86.00 =	\$344.00
[] MULTIPLE DEPENDENT CLAIMS PRESENTED				\$0.00
BASIC FEE				\$770.00
TOTAL				\$1330.00

Please charge any additional required fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

Customer Number: 21186

 By: Marvin L. Beekman
 Atty: Marvin L. Beekman
 Reg. No. 38,377
"Express Mail" mailing label number: EV299683351USDate of Deposit: April 8, 2004

This paper or fee is being deposited on the date indicated above with the United States Postal Service pursuant to 37 CFR 1.10, and is addressed to The Commissioner for Patents, Mail Stop Patent Application, P.O. Box 1450, Alexandria, VA 22313-1450.

S/N Unknown

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Gurtej S. Sandhu et al.

Examiner: Unknown

Serial No.: Unknown

Group Art Unit: Unknown

Filed: Herewith

Docket: 303.085US7

Title: METHOD FOR FORMING A METALLIZATION LAYER

COMMUNICATION CONCERNING RELATED APPLICATION(S)

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Applicants would like to bring to the Examiner's attention the following related application(s) in the above-identified patent application:

<u>Serial/Patent No.</u>	<u>Filing Date</u>	<u>Attorney Docket</u>	<u>Title</u>
09/517684 6171952	March 2, 2000	303.085US3	METHODS OF FORMING METALLIZATION LAYERS AND INTEGRATED CIRCUITS CONTAINING SUCH
10/217618	August 13, 2002	303.085US6	METHOD FOR FORMING A METALLIZATION LAYER

Respectfully submitted,

GURTEJ S. SANDHU ET AL.

By Applicants' Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
P.O. Box 2938
Minneapolis, MN 55402
(612) 373-6960

Date 4-8-04 By Marvin L. Beekman
Marvin L. Beekman
Reg. No. 38,377

"Express Mail" mailing label number: EV299683351US

Date of Deposit: April 8, 2004

This paper or fee is being deposited on the date indicated above with the United States Postal Service pursuant to 37 CFR 1.10, and is addressed to The Commissioner for Patents, Mail Stop Patent Application, P.O. Box 1450, Alexandria, VA 22313-1450.